

# SOT847-1

plastic ball grid array package; 420 balls; body 23 x 23 x 1.7 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA420
<b>Package type industry code</b>	BGA420
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	144E
<b>JEDEC package outline code</b>	MS-034
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	12-2-2004

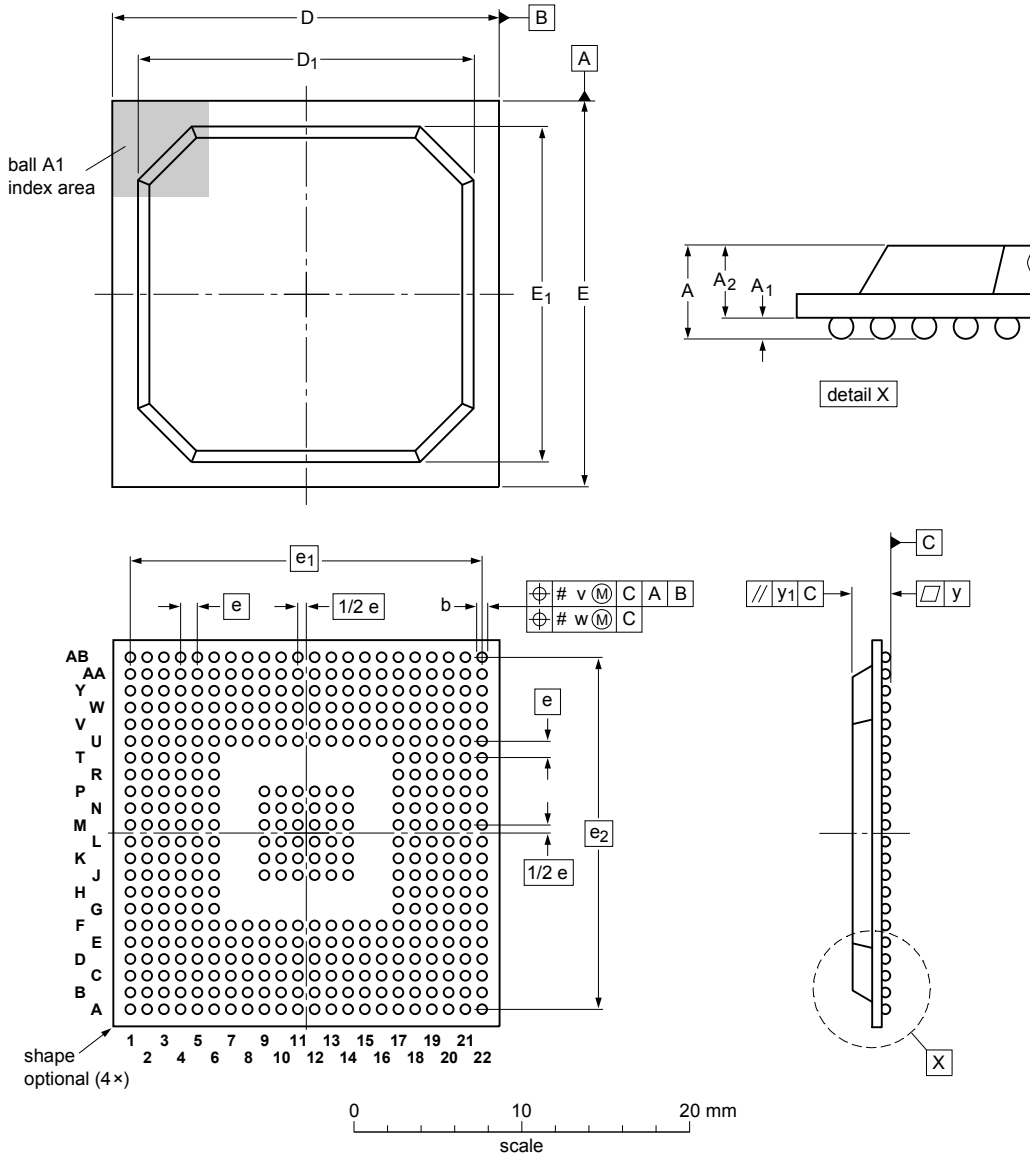
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	22.8	-	23	23.2	mm
E	package width	22.8	-	23	23.2	mm
A	seated height	[tbd]	-	2.4	2.4	mm
A <sub>2</sub>	package height	1.55	-	1.7	1.8	mm
n <sub>2</sub>	actual quantity of termination	-	-	420	-	



## 2. Package outline

BGA420: plastic ball grid array package; 420 balls; body 23 x 23 x 1.7 mm SOT847-1



DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>max</sub>	A <sub>1</sub>	A <sub>2</sub>	b	D	D <sub>1</sub>	E	E <sub>1</sub>	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	2.4	0.6 0.4	1.80 1.55	0.7 0.5	23.2 22.8	20.75 19.75	23.2 22.8	20.75 19.75	1	21	21	0.25	0.1	0.2	0.35

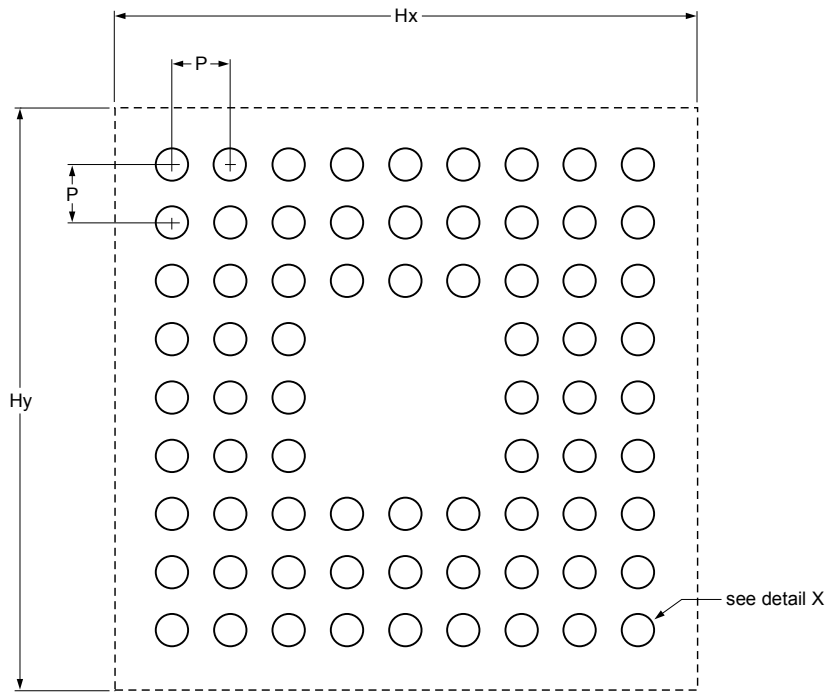
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT847-1	144E	MS-034	---			04-02-12

Fig. 1. Package outline BGA420 (SOT847-1)




### 3. Soldering

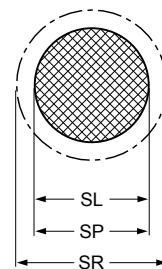
Footprint information for reflow soldering of BGA420 package

SOT847-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
1.00	0.450	0.450	0.600	23.500	23.500

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Fig. 2. Reflow soldering footprint for BGA420 (SOT847-1)

## 4. Legal information

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For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)  
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